

## **PRODUCT SPECIFICATION**

### TITLE

#### 1.0 SCOPE

This Product Specification covers the requirement of USB type C receptacle.

#### 2.0 PRODUCT DESCRIPTION

#### 2.1 PRODUCT NAME AND SERIES NUMBER

Product name: USB type C receptacle Series number: 201267

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS See sales drawing: 201267\*\*\*\*PSD000

#### 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

**Industry Standard Reference:** Universal Serial Bus Type-C Cable and Connector Specification, Revision 1.1, Test standard reference: EIA-364 series, IEC 60068 series

**Test compliant reference:** Universal Serial Bus Type-C Connectors and Cable Assemblies Compliance Document, Revision 1

Dimensions see sales drawings and other sections of this specification for the relevant reference documents. In cases where the specification differs from the drawings, the sales drawings take precedence.

#### 4.0 RATINGS

#### 4.1 VOLTAGE

30 Volts DC/AC Max.

#### 4.2 CURRENT

5 Amps MAX. for total  $V_{BUS}$  pins (Pin A4, A9, B4, B9), 1.25 Amps MAX. for Vconn (B5 of plug) with return path through the corresponding GND pins(Pin A1, A12, B1, B12). 0.25 Amps MIN. for all other contact.

#### 4.3 TEMPERATURE

Operating: Storage:

- 40°C to + 105°C(Including Terminal Temperature Rise)
 - 40°C to + 85°C

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#### 5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5.1.1	Low Level Contact Resistance(LLCR)	Mate connector, The solder tail to the solder tail or cable attachment point of the plug, including any internal contacts and paddle card.Measure at 20 mV (max) open circuit at 100 mA. Per EIA-364-23	40 milliohms Max initial. It is not Exceed 50 milliohms after environmental test.
5.1.2	Insulation Resistance	Mate connector, apply 100 VDC between adjacent terminal or ground. Per EIA-364-21	100Megohms Min.
5.1.3	Dielectric Withstanding Voltage	Mate connector, apply 100 VAC(RMS) for 1 minute between adjacent terminal or ground. Per EIA-364-20 ,Method B.	No breakdown
5.1.4	Temperature Rise /current capability	Mate connector, and measure the temperature rise of contact when the current on power pins are signed as 0.5A,1.0A,1.5A,2A,2.5A,3A,3.5A,4Auntil the T-rise is up to 85°C. Per EIA-364-70,Method 2	emperature change 30°C Max at 5A and Draft the temperature <b>derating curve</b> .

#### 5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5.2.1	Inserting force	Mate connector, at maximum rate 12.5mm/min. Per EIA-364-13	Insertion force: 5~20N
5.2.2	Extraction force	Un-mate connector, at maximum rate 12.5mm/min. Per EIA-364-13	Within the range of 8 N to 20 N. from 1 to 1,000 cycles , within the range of 6 N to 20 N. from 1,000 to 10,000 cycles. within the range of 4 N to 20 N. from 1,000 to 20,000 cycles.
5.2.3	Durability (Total	Perform 4 plug/unplug cycles. Cycle rate of 500+/-50cycles per hour in test Group4	No mechanical damage Contact resistance is not exceed +50 milliohms,
5.2.3	20000 Cycles)	Perform 25 plug/unplug cycles. Cycle rate of 500+/-50cycles per hour in test Group4	No mechanical damage Contact resistance is not exceed +50 milliohms,

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5.2.3 (Conti nue)	Durability (Total	Perform 2468 plug/unplug cycles. Rotate the receptacle or plug 180° and perform 2,500 plug/unplug cycles. Rotate the receptacle or plug 180° and perform 2,500 plug/unplug cycles. Rotate the receptacle or plug 180 and perform 2,500 plug/unplug cycles. Cycle rate of 500+/-50 cycles per hour (Total of 10,000 plug/unplug cycles, flipping every 2,500 cycles). Then, Rotate the receptacle or plug 180 and perform 5,000 plug/unplug cycles. Rotate the receptacle or plug 180 and perform 5,000 plug/unplug cycles. (Total of 20,000 plug/unplug cycles, flipping every 5,000 cycles after 10,000cycles). Per EIA-364-09	No mechanical dama Contact resistance is exceed +50 milliohms	not
5.2.4	Durability (preconditioning)	Perform 50 unplug/plug cycles. Refer to EIA-364-09	No mechanical dama	ge.
5.2.5	Reseating	Manually mate and unmate the connector for 3 cycles. Rate: 5 cycles/min. max. EIA 364-09	No mechanical dama	ge.
5.2.6		Mate connector, The plug should be with cable and over mold, receptacle should be mounted on a 2-layer PCB, PCB thickness is between 0.8 and 1.0mm, the PCB shall be clamped on either side of receptacle no further than 5mm away from the solder tail, 8N tensile force shall be applied to the cable in a Perpendicular direction from interface, period is at least 10 seconds, including 4 orientations. Refer to section 8.0	No any discontinuities Shorting to shell grea than 1µs duration in a four orientations	iter
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#### **5.3 ENVIRONMENTAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5.3.1	Solderability	Um-mate connector, Dip solder tails into the molten solder(held at 240-250°C) up to for in immersion duration 6s. Per EIA 364-52, Category 1.	Solder coverage: 95% Min. No mechanical damage or change to appearance.
5.3.2	Resistance to soldering Heat	Peak temperature in reflow:255°C (- 0/+5°C) .Pb-free reflow profile refer to Section 7.0 ,two cycles. Per EIA 364-56	No mechanical damage or change to appearance s.
5.3.3	Temperature and Humidity (steady state)	Mate connector, Ambient temperature: + $85^{\circ}C \pm 2^{\circ}C$ Chamber humidity: $85 \pm 2$ % RH Test duration: 1008 h. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after which the specified measurements shall be performed. Per EIA-364-31	No mechanical damage. Contact resistance is not exceed 50 milliohms. Insulation resistance not less than 100, Mega ohms. Dielectric strength must meet Item 5.1.2
5.3.4	Thermal Shock	Mate Connector Low temperature TL: -40 °C High temperature TH: 105 °C Dwell time t1 (at TL/TH): 60 min. Transition time: <10 sec. No. of cycles: 100 cycles Refer to IEC 60068-2-14	No mechanical/electrical damage. Contact resistance is not Exceed 50 milliohms.

ITEM	DESCRIPTI ON	TEST CONDITION	REQUIREMENT
5.3.6	Thermal	Mate connector,Cycle the connector between 15°C±3°C and 85°C±3°C, as measured on the part. Ramps should be a minimum of 2°C per minute, and dwell times should insure that contacts reach temperature extreme for a minimum of 5minutes. No humidity control. 10 cycles total.	Contact resistance is not exceed 50 milliohms.

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5.3.7	Vibration	follow vibrati 10~20 15 mi	connectors, and subject t ing vibration conditions, I on 3 mutually perpendic 000Hz, 0.02g2/Hz nutes per plane IA-364-28 condition VII, 1	Random ular axes,	Contact exceed 5	nanical dam resistance i 0 milliohms scontinuity	is not
5.3.8	Mixed flowing gas test	Samp enviro that is for co gas m used a 30u'ge plating flash f Note:	connectors. les should be placed in a onmentally controlled 'tes monitored by a gas anal ntrolled concentrations of nixture. Test coupons sha and the weight gain repor- old or Gold flash& 30u'Pc g for 7 days.15u'gold for for 3 days.	esistance n 0 milliohms			
5.3.9	Temperature life	condit	onnectors, and subject to the ons of 105°C for 120 hours. A-364-17 condition A				
5.3.1		condit	te connectors, and subject to the iditions of 105°C for 72 hours. EIA-364-17 condition A No mechanical damag Visible corrosion. Contact resistance is r exceed 50 milliohms.				
5.3.1	1 Mechanical Shock	Shock Accelo Shock No. of	connectors, wave form: half sinusoic eration: 50 g duration (nominal): 11 n shocks: 10 per direction to IEC 60068-2-29	າຣ	Contact r	anical dama esistance is 0 milliohms	s not
5.3.1	2 Dry Heat	High t Dwell	connectors, emperature TH: 105°C time at TH: 1000 h to IEC 60068-2-2 and		damage. resistanc		
	-	mecha corros problen of platir plating ts	anical damage" in the tal ion at contact area n of plating ng	ble above is:	1		1
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#### 5.0 TEST GROUPINGS

Test Item	Description	Group1	Group2	Group3	Group4	Group5	Group6	Group7	Group8	Group9	Group 10	Group 11
5.1.1	Low level contact resistance	1,4, 6	1,4, 6,8	1,4, 6	1,4, 6,8, 10	2, 10					1,5	1,6
5.2.4	Durability (preconditionin g)	2	2	2	2							
5.1.2	Insulation resistance					12						2,7
5.1.3	Dielectric withstanding voltage					1, 11						
5.3.10	Temperature life (Preconditionin g)			3	3							
5.3.9	Temperature life	3										
5.3.4	Thermal shock		3									
5.3.6	Thermal disturbance				7							
5.3.3	Cyclic temperature & humidity		5									
5.3.8	Mixed flowing gas				5							
5.3.7	Vibration			5								
5.2.5	Reseating	5	7		9							
5.1.4	Temperature rise							1				
5.2.1	Insertion force					4				2	2,6	3,8
5.2.2	Extraction force					5,7,9				3	3,7	4,9
	Durability (4 cycles)					3						
5.2.3	Durability (25cycles)					6						
	Durability (total 20000cycles)					8						
5.3.1	Solderability								1			
5.3.2	resistance to soldering Heat testing									1		
5.2.6	4-Axis Continuity Test						1					
5.3.11	Mechanical Shock										4	
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5.3.12	Dry Heat											5
	Sample Quantity	5	5	5	5	5	5	5	5	5	10	10

#### 6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage. Samples in the delivery condition shall be passed drop test with 1m height from concrete floor. The parts will be carried in tape & reels inside boxes. For detail package refer to packaging spec.

#### 7.0 Recommended reflow profile

#### Reflow profile for soldering heat resistance testing



Time and temperature requirements:

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Pb-free reflow profile requirements for soldering heat resistance					
Parameter	Reference	Specification			
Average temperature gradient in preheating		2.5°C/s			
Soak time	t <sub>soak</sub>	2-3 minutes			
Time above 217°C	t <sub>1</sub>	Max 60 s			
Time above 230°C	t <sub>2</sub>	Max 50 s			
Time above 255°C±5°C	t <sub>3</sub>	Min 5 s			
Peak temperature in reflow	T <sub>peak</sub>	255°C (–0/+5°C)			
Temperature gradient in cooling		Max -5°C/s			

Notes:

1: Reflow soldering profile for solderability testing and soldering heat resistance testing

2: Temperature indicated refers to the PCB surface temperature at soldertail area.

3: Connector can withstand up to 2 reflow cycles with a cool-down to room temperature inbetween.

4: Actual reflow profile also depends on equipment, solder paste, PCB thickness, and other components on the board. Please consult your solder paste & reflow equipment manufacturer for their recommendations to adopt a suitable process.

#### 8.0 4-Axis Continuity Test

Detailed information refer to USB Type-C industry standard or its compliance document.

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